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US 6,625,037 C1 (5997th)

PRINTED CIRCUIT BOARD AND METHOD MANUFACTURING THE SAME

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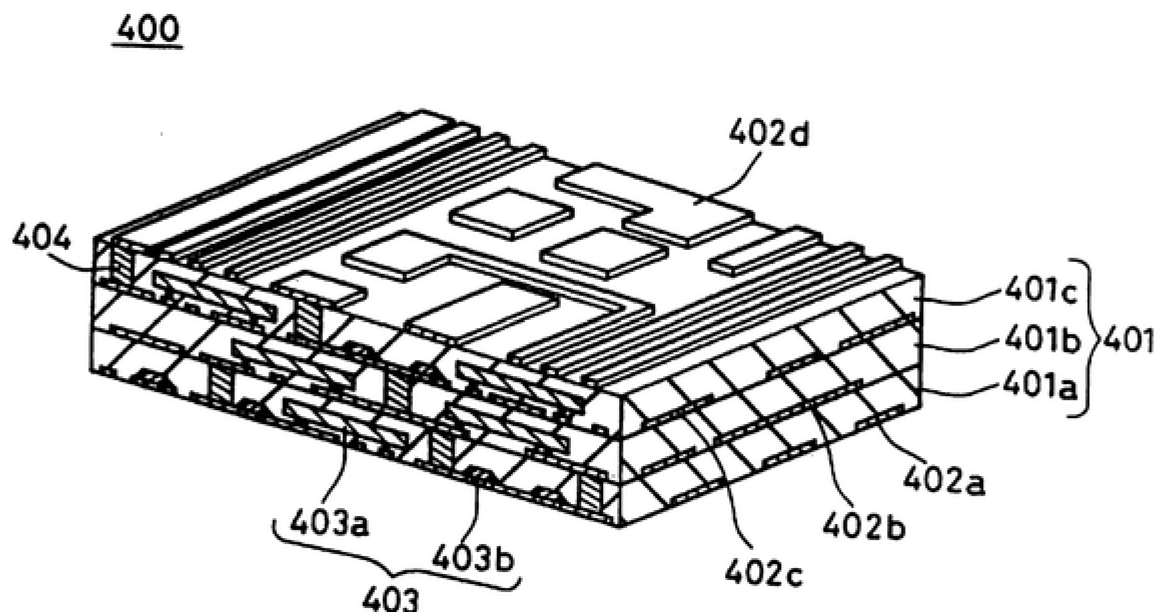
Reexamination Certificate for Patent 6,625,037, issued Sep. 23, 2003, Appl. No. 956,551, Sep. 20, 2001.

Division of application No. 09/484,899, filed on Jan. 18, 2000, now Pat. No. 6,338,767, which is a division of application No. 09/196,792, filed on Nov. 20, 1998, now Pat. No. 6,038,133.

Claims priority, application Japan, Nov. 25, 1997, 9-322595

Int. Cl. H01L *23/12;21/02;23/28;23/31;23/14;21/56;25/065;25/10;* **H05K** *3/46;3/20;1/18;3/40;1/03* (2006.01)

U.S. Cl. 361—762



AS A RESULT OF REEXAMINATION, IT HAS BEEN DETERMINED THAT:

Claims **15**-**23** are cancelled.

Claims **1** and **8** are determined to be patentable as amended.

Claims **2**-**7** and **9**-**14**, dependent on an amended claim, are determined to be patentable.

1. A circuit component built-in module comprising:

at least two *single layer* insulating substrates*, each single layer insulating substrate being in direct contact with at least one other single layer insulating substrate, and each single layer* comprising an inner via and a wiring pattern; *and*

[a]*one or more* circuit [component]*components* formed within [at least one]*each single layer* insulating substrate*,* [of the at least two insulating substrates, said]*each of said one or more* circuit [component] *components* being electrically connected to [the]*at least one* inner via and [the]*at least one* wiring pattern,

wherein the at least one insulating substrate is formed of a mixture comprising **70** wt % to **95** wt % of an inorganic filler and a thermosetting resin.